# DSC612PL2A-0130



## **Two-Output Low Power MEMS Clock Generator**

# **General Description**

The DSC612PL2A-0130 is a two-output low power MEMS clock generator.

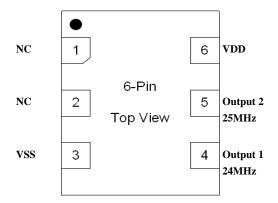
The MEMS based clock generator eliminates the need of external crystal or reference clock.

Refer to DSC612 master data sheet to read full descriptions.

#### **Features**

- Two LVCMOS clock outputs: 24MHz, 25MHz
- Ultra-small package size: 1.6mm x 1.2mm 6L LGA
- High stability: ±25ppm
- Temperature range: -40°C to +105°C
- Low power consumption: ~5mA (both outputs active)
- Wide supply voltage range: 1.71V -3.63V VDD
- Excellent shock and vibration immunity
- High reliability
- Lead free and RoHS compliant
- AEC-Q100 automotive grade available

# **Pin Configuration and Description**



6-pin 1.6mm x 1.2mm 6L LGA

Pin Number	Pin Name	Pin Type	Pin Description
1	NC	I	Non-functional, do not connect
2	NC	I	Non-functional, do not connect
3	VSS	Power	Power Supply Ground
4	Output 1	О	24MHz LVCMOS Clock Output
5	Output 2	О	25MHz LVCMOS Clock Output
6	VDD	Power	Power Supply

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## **Ordering Information**

Ordering Part Number	Temperature Range	High Stability	Shipping	Package
DSC612PL2A-0130	-40°C to +105°C	±25ppm	Bag	1.6mm x 1.2mm 6L LGA
DSC612PL2A-0130T	-40°C to +105°C	±25ppm	Tape and Reel	1.6mm x 1.2mm 6L LGA

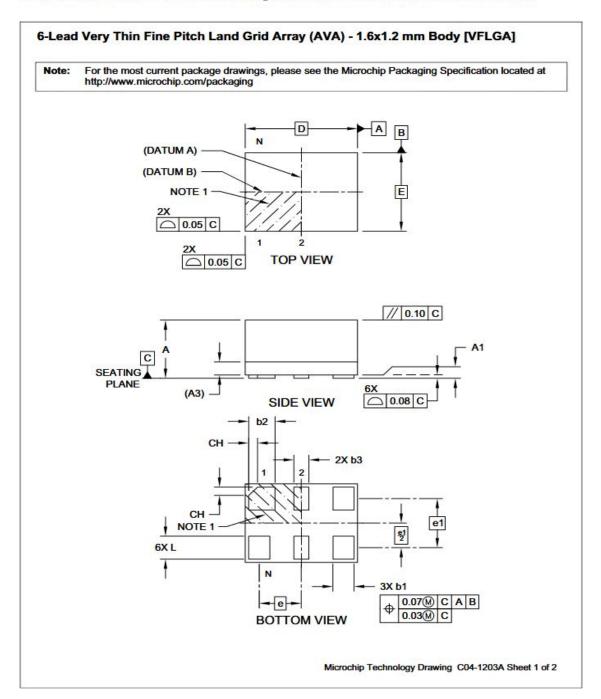
Devices are Green and RoHS compliant. Sample material may have only a partial top mark.

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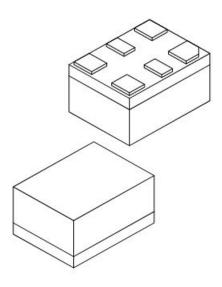
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6-Lead 1.6 mm x 1.2 mm VFLGA Package Outline and Recommended Land Pattern



### 6-Lead Very Thin Fine Pitch Land Grid Array (AVA) - 1.6x1.2 mm Body [VFLGA]

For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Terminals	N	6		
Terminal Pitch	е	0.60 BSC		
Terminal Pitch	e1	0.75 BSC		
Overall Height	Α	0.79	0.84	0.89
Standoff	A1	0.00	0.02	0.05
Substrate Thickness (with Terminals)	A3	0.20 REF		
Overall Length	D	1.60 BSC		
Overall Width	E	1.20 BSC		
Terminal Width	b1	0.25	0.30	0.35
Terminal Width	b2	0.325	0.375	0.425
Terminal Width	b3	0.20	0.25	0.30
Terminal Length	L	0.30	0.35	0.40
Terminal 1 Index Chamfer	CH	-	0.125	- 1

#### Notes:

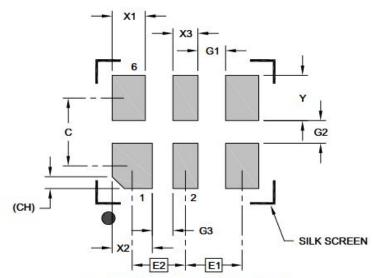
- Pin 1 visual index feature may vary, but must be located within the hatched area.
  Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances. REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1203A Sheet 2 of 2

### 6-Lead Very Thin Fine Pitch Land Grid Array (AVA) - 1.6x1.2 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS			
Dimension	on Limits	MIN	NOM	MAX	
Contact Pitch (X3)	E1	0.60 BSC			
Contact Pitch	E2		0.56 BSC		
Contact Spacing	С		0.75		
Contact Width (X3)	X1			0.35	
Contact Width	X2		1 1	0.43	
Contact Width (X2)	Х3			0.27	
Contact Pad Length (X6)	Y			0.50	
Space Between Contacts (X4)	G1	0.29			
Space Between Contacts (X3)	G2	0.25			
Space Between Contacts	G3	0.22			
Contact 1 Index Chamfer	CH	0.13 X 45° REF			

#### Notes

Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-3203A